

P-channel enhancement mode vertical DMOS FET

ZETEX SEMICONDUCTORS

ZVP1320**FEATURES**

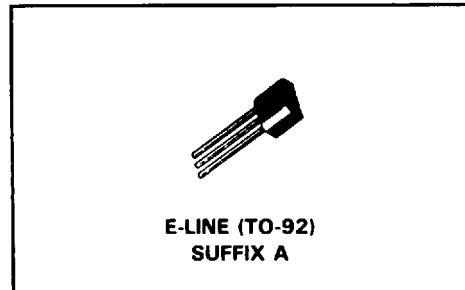
- Compact geometry
- Fast switching speeds
- No secondary breakdown
- Excellent temperature stability
- High input impedance
- Low current drive
- Ease of paralleling

DESCRIPTION

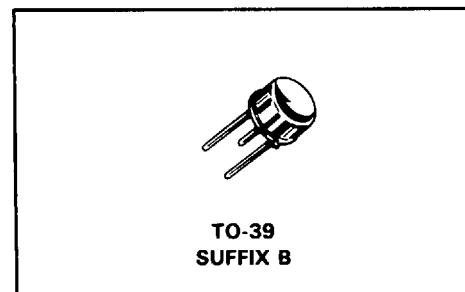
A compact interdigitated geometry forms the basis of this Zetex MOSFET. Optimised for low on-resistance, low capacitance and fast switching, this device is manufactured using the latest computer controlled processing techniques in order to achieve greater stability, reliability and ruggedness.

PRODUCT SUMMARY

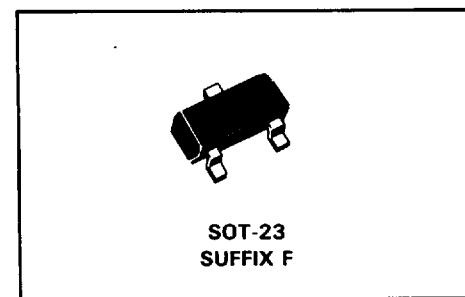
Part No.	BV_{DSS}	I_D	$R_{DS(on)}$
ZVP1320A	- 200V	- 0.07 A	80Ω
ZVP1320B	- 200V	- 0.10 A	80Ω
ZVP1320F	- 200V	- 0.035 A	80Ω



E-LINE (TO-92)
SUFFIX A



TO-39
SUFFIX B



SOT-23
SUFFIX F

ZVP1320**ZETEX SEMICONDUCTORS****ABSOLUTE MAXIMUM RATINGS**

Parameters		E-line	TO-39	SOT-23	Units
V_{DS}	Drain-source voltage	-200	-200	-200	V
I_D	Continuous drain current (@ $T_A = 25^\circ\text{C}$)	-0.07	-0.07	-0.035	A
I_D	Continuous drain current (@ $T_C = 25^\circ\text{C}$)	-	-0.10	-	A
I_{DM}	Pulsed drain current	-0.4	-0.4	-0.4	A
V_{GS}	Gate-source voltage	± 20	± 20	± 20	V
P_D	Max. power dissipation (@ $T_A = 25^\circ\text{C}$)	0.625	0.625	0.25	W
P_D	Max. power dissipation (@ $T_C = 25^\circ\text{C}$)	-	5	-	W
T_J, T_{stg}	Operating/storage temperature range	-55 to +150			°C

ELECTRICAL CHARACTERISTICS (at $T = 25^\circ\text{C}$ unless otherwise stated)

Parameter	Min.	Max.	Unit	Conditions
BV_{DSS}	Drain-source breakdown voltage	-200	-	V $I_D = -1\text{mA}, V_{GS} = 0\text{V}$
$V_{GS(th)}$	Gate-source threshold voltage	-1.5	-3.5	V $I_D = -1\text{mA}, V_{DS} = V_{GS}$
I_{GSS}	Gate-body leakage	-	20	nA $V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
I_{DSS}	Zero gate voltage drain current	-	-10	$\mu\text{A} V_{DS} = \text{Max. rating}, V_{GS} = 0\text{V}$
		-	-50	$\mu\text{A} V_{DS} = 0.8 \times \text{Max. rating}$ $V_{GS} = 0\text{V} (T = 125^\circ\text{C})$ (2)
$I_{D(on)}$	On-state drain current (1)	-100	-	mA $V_{DS} = -25\text{V}, V_{GS} = -10\text{V}$
$R_{DS(on)}$	Static drain-source on-state resistance (1)	-	80	Ω $I_D = -50\text{mA}, V_{GS} = -10\text{V}$
g_{fs}	Forward transconductance (1) (2)	25	-	mS $V_{DS} = -25\text{V}, I_D = -50\text{mA}$
C_{iss}	Input capacitance (2)	-	50	pF (2) $V_{DS} = -25\text{V}, V_{GS} = 0\text{V}$ $f = 1\text{MHz}$
C_{oss}	Common source output capacitance (2)	-	15	pF
C_{rss}	Reverse transfer capacitance (2)	-	5	pF
$t_{d(on)}$	Turn-on delay time (2) (3)	-	8	ns (3) $V_{DD} \approx -25\text{V}, I_D = -50\text{mA}$
t_r	Rise time (2) (3)	-	8	ns
$t_{d(off)}$	Turn-off delay time (2) (3)	-	8	ns
t_f	Fall time (2) (3)	-	16	ns

(1) Measured under pulsed conditions. Width = 300μs. Duty cycle ≤ 2%.

(2) Sample test.

(3) Switching times measured with 50Ω source impedance and < 5ns rise time on a pulse generator.

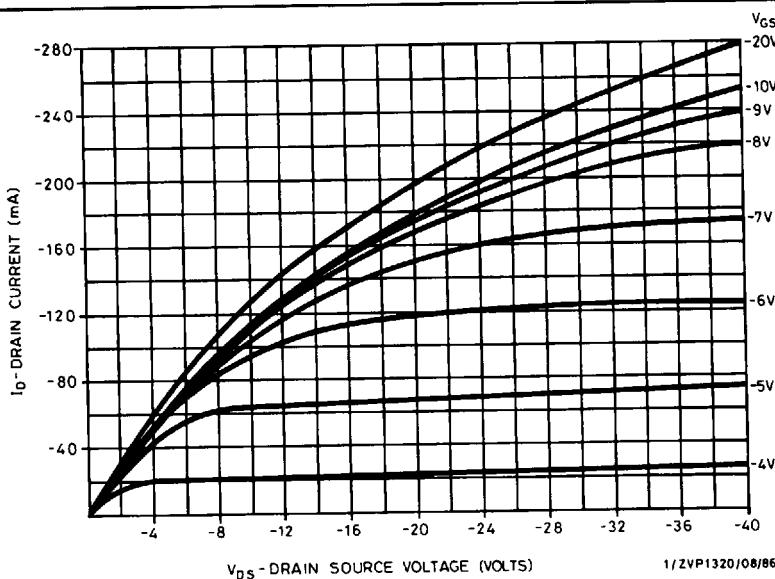


Fig. 1 Typical output characteristics

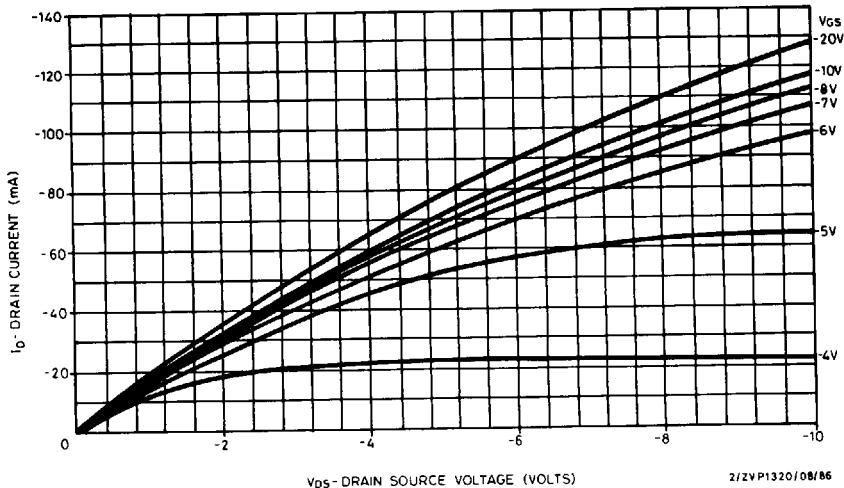
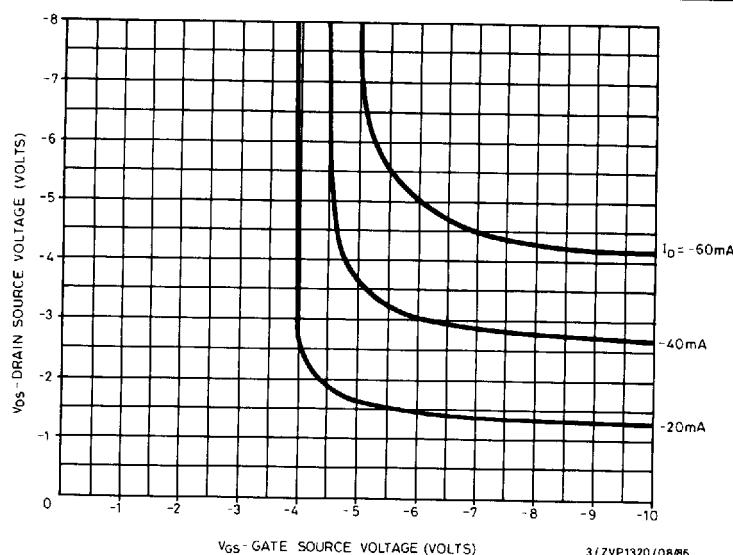
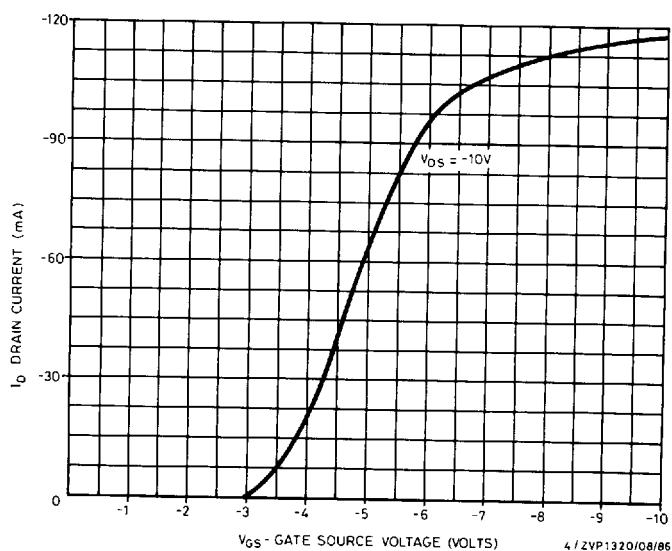


Fig. 2 Typical saturation characteristics

ZVP1320**ZETEX SEMICONDUCTORS****Fig. 3 Typical voltage saturation characteristics****Fig. 4 Typical transfer characteristics**

ZETEX SEMICONDUCTORS

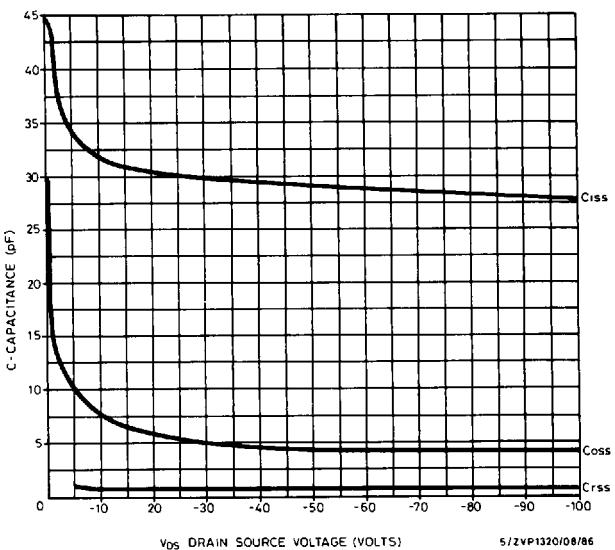


Fig. 5 Typical capacitance v drain-source voltage

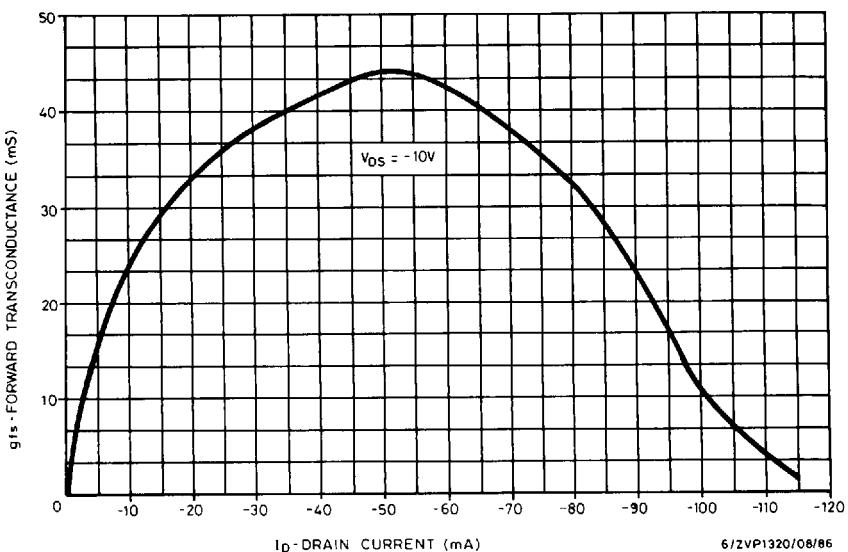
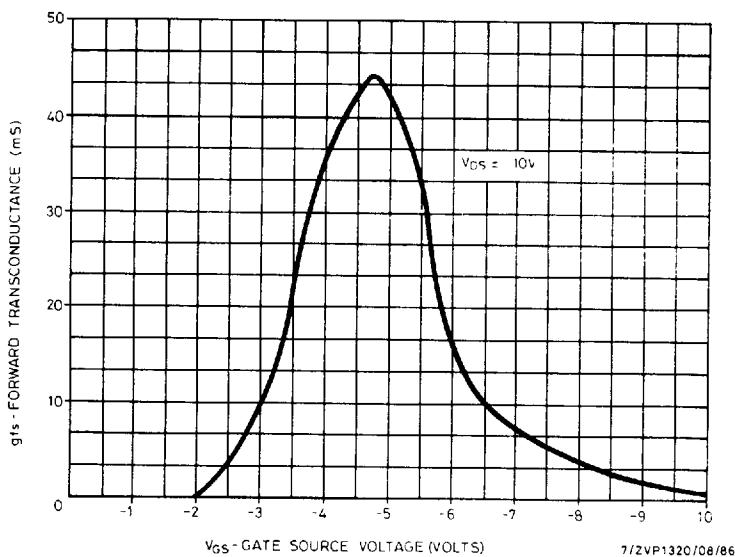
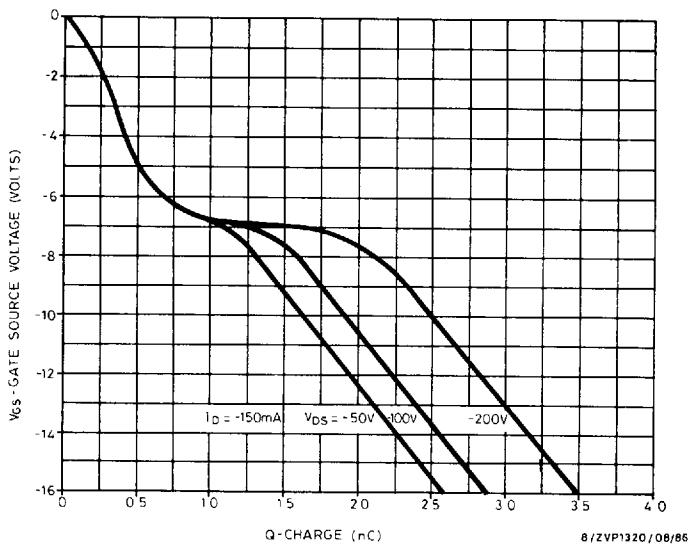


Fig. 6 Typical transconductance v drain current

ZVP1320**ZETEX SEMICONDUCTORS****Fig. 7 Typical transconductance v gate-source voltage**

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**Fig. 8 Typical gate charge v gate-source voltage**

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ZETEX SEMICONDUCTORS

ZVP1320

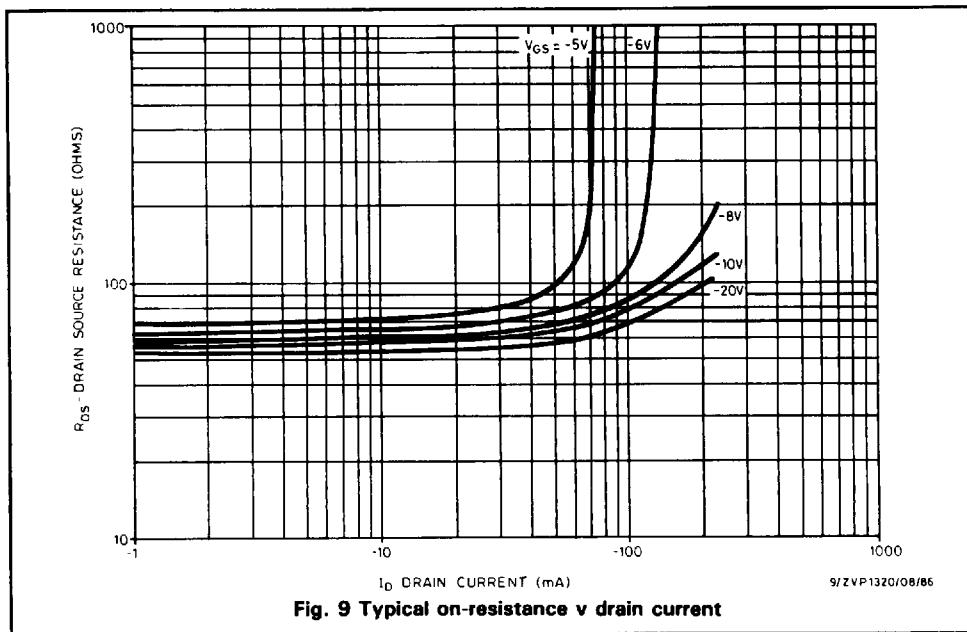
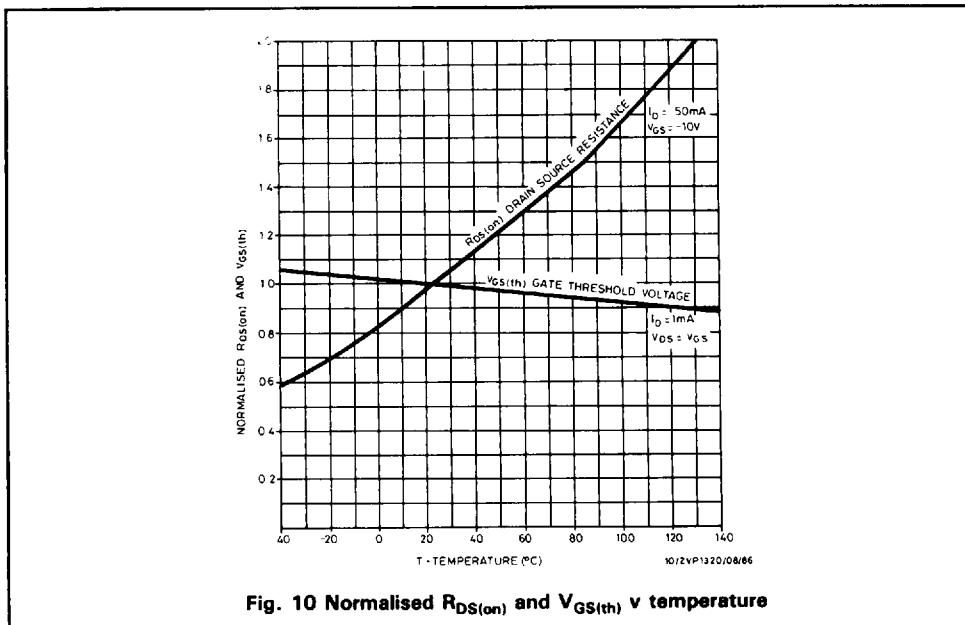
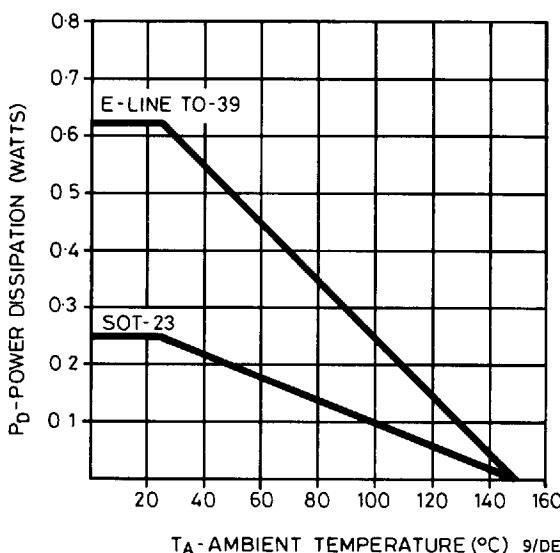
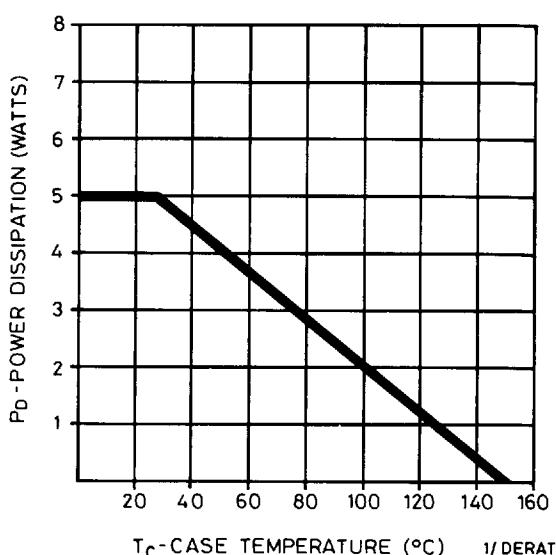


Fig. 9 Typical on-resistance v drain current

Fig. 10 Normalised $R_{DS(on)}$ and $V_{GS(th)}$ v temperature

ZVP1320**ZETEX SEMICONDUCTORS****Fig. 11 Power v temperature derating curve (ambient)****Fig. 12 Power v temperature derating curve (case)**